



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
 [List multiple models if applicable.]

HP t5740e Thin Clients

Name / Model #2

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

- 1.1 Items listed below are classified as requiring selective treatment.
- 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Phillips screwdriver	
Description #2 Dikes	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. To remove the secure USB compartment cover (see Figure 1):
 - a. On rear of the thin client, remove the screw that secures the compartment cover to the unit (1).
 - b. On the front of the unit, push the compartment cover about 1.27 cm (1/2 inch) toward the front of the unit (2).
 - c. Remove the cover from the unit by first lifting the rear (screw side) of the cover, and then lifting the cover off the unit (3).
2. To remove the access panel (see Figure 2):
 - a. Remove the secure compartment cover (1).
 - b. Remove the stand, if it is installed (2).
 - c. Slide the access panel about 6.35 mm (1/4 inch) toward the top of the unit (3), and then lift the access panel up and off the unit (4)..
3. To remove the metal side cover (see Figure 3):
 - a. Remove the four screws that secure the metal side cover to the chassis (1).
 - b. Lift the metal side cover, front side first, off the unit (2).
4. To remove the battery, gently push the metal guard that extends above one edge of the battery very slightly toward the rear of the unit (1), and then lift the battery out (2) (see Figure 4).
5. To remove the system board:
 - a. Loosen the two captive screws from the small heat sink and the four captive screws from the large heat sink and remove the heat sinks from the system board (see Figure 5).
 - b. On the rear of the unit, remove the two hex screws from each side of the video port and two hex screws from each side of the serial port (see Figure 6).
 - c. Remove the five screws that secure the system board to the thin client chassis (see Figure 7).
 - d. Unplug the speaker cable from the system board.
 - e. Remove the rear I/O panel by lifting the panel upward, and then rotating the top of the panel away from the chassis and pulling it away from the chassis.
 - f. Remove the system board from the unit.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

FIGURE 1: Removing the secure USB compartment cover

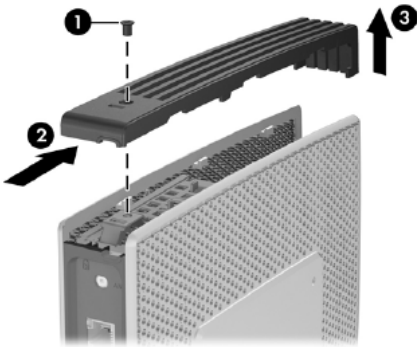


FIGURE 2: Removing the access panel

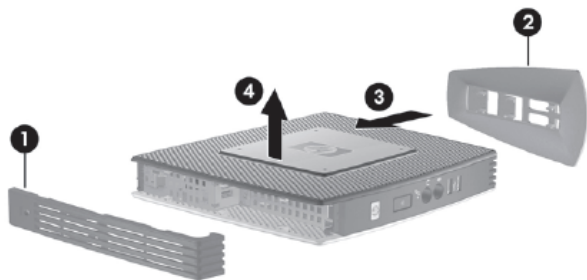


FIGURE 3: Removing the metal side cover

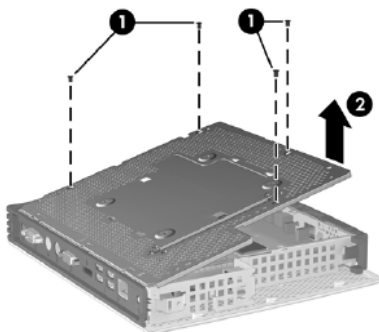


FIGURE 4: Battery removal

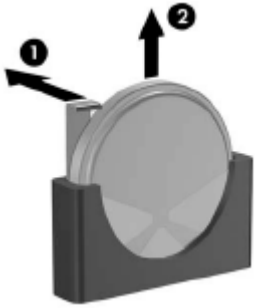


FIGURE 5: Heat sink screw locations

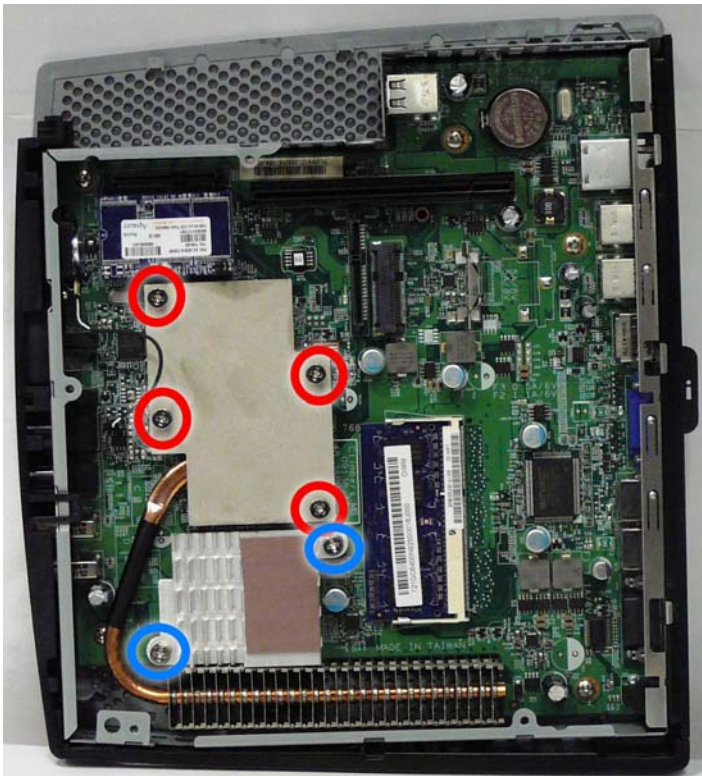


FIGURE 6: System board screw locations

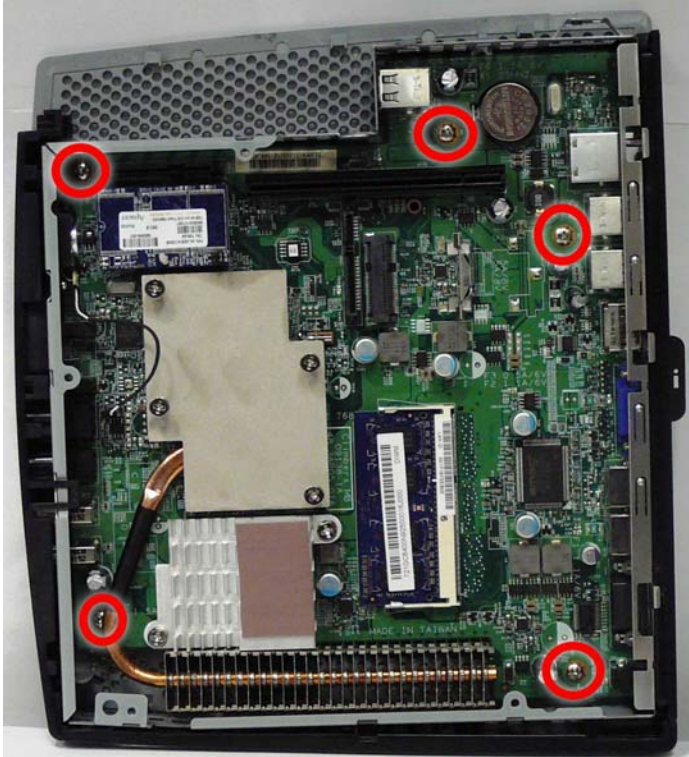


FIGURE 7: Hex screw locations (rear of unit)

